

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) An optical communications module comprising:
one or more dielectric wiring substrates and a chassis,
said one or more dielectric wiring substrates having an optical transmitter section, an optical receiver section, or an optical transceiver section provided thereon, the chassis encasing all of the dielectric wiring substrates including said optical transmitter section, said optical receiver section or said optical transceiver section provided thereon,
at least one of said dielectric wiring substrates having a metal part formed on one side thereof, said metal part being exposed as an outermost surface of the chassis.
2. (Currently Amended) An optical communications module according to claim 1,
wherein said at least one dielectric wiring substrate having the metal part formed on one side thereof comprises a metal base substrate.
3. (Currently Amended) An optical communications module according to claim 1,
wherein said dielectric wiring substrates are thermally connected together through a metal part of said chassis.
4. (Currently Amended) An optical communications module according to claim 1,
wherein said dielectric wiring substrates are thermally separated from each other.
5. (Original) An optical communications module according to claim 1, wherein said chassis has one or more vents.